

H330S HSPA+ Module

Perfect Wireless Experience

Quad-band
GSM/GPRS/EDGE

Quad-band HSPA/HSPA+

5.76Mbps HSUPA

21Mbps HSDPA

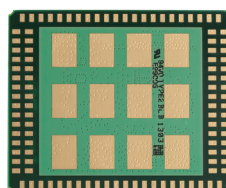
Internal TCP/IP & UDP/IP

Temperature Range
-40°C~+85°C

Analog and Digital Audio

FIBOCOM H330S LGA模块, 采用业界领先的Intel平台, 支持全球主要3G频段。为客户提供丰富的应用接口, 包括USB2.0、UART、I2C、I2S, 内置TCP/IP和UDP/IP协议栈, 灵活性强, 易于集成。

H330S LGA模块可应用于车载导航、安防监控、无线POS和远程医疗等工业领域, 亦可应用于平板电脑和电子书等消费电子, 满足用户对移动宽带的消费需求。



适用于

- 全球市场

H330S HSPA+ Module

Perfect Wireless Experience

H330S HSPA+ Module Technical Specifications

产品特性

- WCDMA: Band 1,2,5,8 or Band 1,8
- GSM/GPRS/EDGE: 850/900/1800/1900MHz or 900/1800MHz
- LGA 120pin 33.8 x 27.8 x 2.45mm
- Operating Temperature: -30 ~ +75°C
Storage Temperature: -40 ~ +85°C
- Operating Voltage: DC 3.3V~4.2V, Typical 3.8V
- TX Power
 - UMTS/HSPA+ Class 3 (0.25W)
 - GSM 850/900 MHz Class 4 (2W)
 - GSM 1800/1900 MHz Class 1 (1W)
 - EDGE 850/900 MHz Class E2 (0.5W)
 - EDGE 1800/1900 MHz Class E2 (0.4W)
- AT Command Set: FIBOCOM proprietary AT commands/
GSM 07.05/GSM 07.07

数据特性

- UMTS/HSDPA/HSUPA 3GPP release 7
HSUPA 5.76Mbps (Cat 6)
HSDPA 21Mbps (Cat 14)/7.2Mbps (Cat 8)
- GSM 3GPP release 7
EDGE (E-GPRS) Multi-slot class 33 (296kbps DL,
236.8kbps UL)
GPRS Multi-slot class 33 (107kbps DL, 85.6kbps UL)
- MUX:
Basic Mode
- SMS:
MO/MT Text and PDU modes
Cell broadcast
- Embedded TCP/IP and UDP/IP protocol stack

接口

- SIM Card: 1.8V/3.0V
- Multiple Profiles over USB
- 1 x USB 2.0 Multi-endpoints
- 2 x UART
- MUX Over UART1
- PCM
- I2C
- I2S
- GPIO
- RTC
- HSIC
- A/D

驱动

- Win CE
- Linux 2.6.18 above
- Android 4.2 above



认证

- CCC/RoHS/CE-RED/GCF/FCC/PTCRB/JRF/RCM/ANATEL

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